



25th International Conference on Electronic Packaging Technology

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Speech subject: **Research on Defect Inspection Technology for Bumping in IC Packaging**

Speech leader: Zili Zhang, Researcher, Institute of Microelectronics, Chinese Academy of Sciences

Speech Description/Objective:

Speech Outline:

Who Should Attend:

Introduction of Speaker:

Zili Zhang is Researcher of Institute of Microelectronics, Chinese Academy of Sciences, Ph.D. supervisor and Professor of University of Chinese Academy of Sciences. Dr Zhang serves as Committee member of Geometric Quantity Professional Committee of the Chinese Society for Measurement and Online Inspection Technology and Intelligent Manufacturing Professional Committee of the Chinese Society for Measurement. She is Project Review Expert of National Key Research and Development Program and National Natural Science Foundation. She received PhD degree in Measurement Technology and Instruments from Tianjin University in China in 2010. Her research interests include industrial precision measurement technology, photoelectric testing technology, defect inspection in Integrated Circuits, Computer vision and Image processing. She has published 44 journal and conference papers and has applied for 45 patents and held 26 patents. As Project Leader, She has presided over projects of National Key Research and Development Program and National Natural Science Foundation. She also participated in research on many projects of National Natural Science Foundation, Major Special Projects of Ministry of Science and Technology, projects of National Key R&D Program and Equipment Projects of the Chinese Academy of Sciences. She has won the Grand Prize in the Technology Invention Award of Chinese Mechanical Engineering Society and the First Prize of Science and Technology Progress Award of Chinese Mechanical Engineering Society.